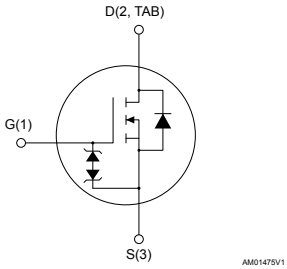
N-channel 525 V, 0.95 Ω typ., 6 A, SuperFREDmesh3™ Power MOSFETs in DPAK and TO-220FP packages



Features

Order codes	V_{DS}	$R_{DS(on)}$ max.	I_D	P_{TOT}
STD7N52DK3	525 V	1.15 Ω	6 A	90 W
STF7N52DK3				25 W

- 100% avalanche tested
- Extremely high dv/dt capability
- Gate charge minimized
- Very low intrinsic capacitance
- Improved diode reverse recovery characteristics
- Zener-protected

Applications

- Switching applications

Description

These devices are developed using the revolutionary N-channel SuperFREDmesh3™ technology. They associate all advantages of reduced on-resistance, Zener gate protection and very high dv/dt capability with a fast body-drain recovery diode. Such series complements the FDmesh™ advanced technology.

Product status links
STD7N52DK3
STF7N52DK3

Product summary	
STD7N52DK3	
Order code	STD7N52DK3
Marking	7N52DK3
Package	DPAK
Packing	Tape and reel
STF7N52DK3	
Order code	STF7N52DK3
Marking	7N52DK3
Package	TO-220FP
Packing	Tube

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value		Unit
		DPAK	TO-220FP	
V_{DS}	Drain-source voltage	525		V
V_{GS}	Gate-source voltage	±30		V
I_D	Drain current (continuous) at T_C = 25 °C	6	6(1)	A
	Drain current (continuous) at T_C = 100 °C	4	4(1)	A
I_{DM}(2)	Drain current (pulsed)	24	24(1)	A
P_{TOT}	Total dissipation at T_C = 25 °C	90	25	W
I_{AR}(3)	Avalanche current, repetitive or non-repetitive	3		A
E_{AS}(4)	Single pulse avalanche energy	110		mJ
dv/dt(5)	Peak diode recovery voltage slope	20		V/ns
di/dt(5)	Diode reverse recovery current slope	400		A/ns
V_{ISO}	Insulation withstand voltage (RMS) from all three leads to external heat sink (t = 1 s, T_C = 25 °C)		2.5	kV
T_{stg}	Storage temperature range	-55 to 150		°C
T_J	Operating junction temperature range			

1. *This value is limited by maximum junction temperature.*
2. *Pulse width is limited by safe operating area.*
3. *Pulse width is limited by T_{Jmax}.*
4. *Starting T_J = 25 °C, I_D = I_{AR}, V_{DD} = 50 V*
5. *I_{SD} ≤ 6 A, $V_{DS(peak)}$ ≤ $V_{(BR)DSS}$, V_{DD} = 80% $V_{(BR)DSS}$*

Table 2. Thermal data

Symbol	Parameter	Value		Unit
		DPAK	TO-220FP	
$R_{thj\text{-}case}$	Thermal resistance junction-case	1.39	5	°C/W
$R_{thj\text{-}pcb}$(1)	Thermal resistance junction-pcb	50		°C/W
$R_{thj\text{-}amb}$	Thermal resistance junction-ambient		62.5	°C/W

1. *When mounted on an 1-inch² FR-4, 2oz Cu board.*

2 Electrical characteristics

(T_C = 25 °C unless otherwise specified)

Table 3. On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	I_D = 1 mA, V_{GS} = 0 V	525			V
I_{DSS}	Zero gate voltage drain current	V_{GS} = 0 V, V_{DS} = 525 V			1	µA
		V_{GS} = 0 V, V_{DS} = 525 V, T_C = 125 °C(1)			50	µA
I_{GSS}	Gate body leakage current	V_{GS} = ±20 V, V_{DS} = 0 V			±10	µA
$V_{GS(th)}$	Gate threshold voltage	V_{DS} = V_{GS}, I_D = 50 µA	3	3.75	4.5	V
$R_{DS(on)}$	Static drain-source on-resistance	V_{GS} = 10 V, I_D = 3 A		0.95	1.15	Ω

1. *Defined by design, not subject to production test.*

Table 4. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	V_{DS} = 50 V, f = 1 MHz, V_{GS} = 0 V	-	870	-	pF
C_{oss}	Output capacitance			70		
C_{rss}	Reverse transfer capacitance			13		
$C_{oss(tr)}$(1)	Time-related equivalent output capacitance	V_{DS} = 0 to 420 V, V_{GS} = 0 V	-	53	-	pF
$C_{oss(er)}$(2)	Energy-related equivalent output capacitance		-	74	-	pF
R_G	Intrinsic gate resistance	f = 1 MHz open drain	-	3.5	-	Ω
Q_g	Total gate charge	V_{DD} = 420 V, I_D = 6 A, V_{GS} = 0 to 10 V (see Figure 17. Test circuit for gate charge behavior)	-	33	-	nC
Q_{gs}	Gate-source charge			5		
Q_{gd}	Gate-drain charge			19		

1. *$C_{oss(tr)}$ is defined as the constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 420 V.*
2. *$C_{oss(er)}$. is defined as the constant equivalent capacitance giving the same stored energy as C_{oss} when V_{DS} increases from 0 to 420 V.*

Table 5. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	V_{DD} = 260 V, I_D = 3 A, R_G = 4.7 Ω, V_{GS} = 10 V (see Figure 16. Test circuit for resistive load switching times and Figure 21. Switching time waveform)	-	12	-	ns
t_r	Rise time			12		
$t_{d(off)}$	Turn-off delay time			37		
t_f	Fall time			19		

Table 6. Source-drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		6	A
I_{SDM}(1)	Source-drain current (pulsed)				24	
V_{SD}(2)	Forward on voltage	I_{SD} = 6 A, V_{GS} = 0 V	-		1.5	V
t_{rr}	Reverse recovery time	I_{SD} = 6 A, di/dt = 100 A/µs,	-	110		ns
Q_{rr}	Reverse recovery charge	V_{DD} = 60 V		0.44		µC
I_{RRM}	Reverse recovery current	(see Figure 18. Test circuit for inductive load switching and diode recovery times)		8		A
t_{rr}	Reverse recovery time	I_{SD} = 6 A, di/dt = 100 A/µs,	-	140		ns
Q_{rr}	Reverse recovery charge	V_{DD} = 60 V, T_j = 150 °C		0.68		µC
I_{RRM}	Reverse recovery current	(see Figure 18. Test circuit for inductive load switching and diode recovery times)		10		A

1. *Pulse width limited by safe operating area.*
2. *Pulsed: pulse duration = 300 µs, duty cycle 1.5%.*

Table 7. Gate-source Zener diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)GSO}$	Gate-source breakdown voltage	I_{GS} = ±1 mA, I_D = 0 A	30	-	-	V

The built-in back-to-back Zener diodes are specifically designed to enhance the ESD performance of the device. The Zener voltage facilitates efficient and cost-effective device integrity protection, thus eliminating the need for additional external componentry.

2.1 Electrical characteristics (curves)

Figure 1. Safe operating area for DPAK

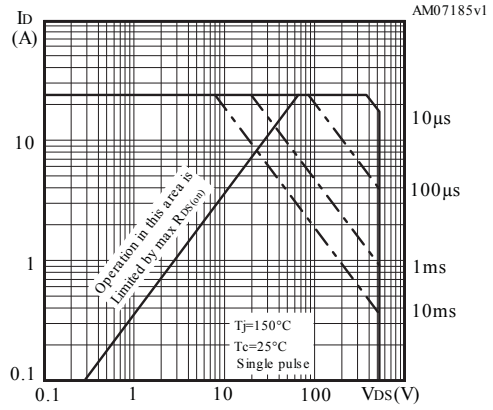


Figure 2. Thermal impedance for DPAK

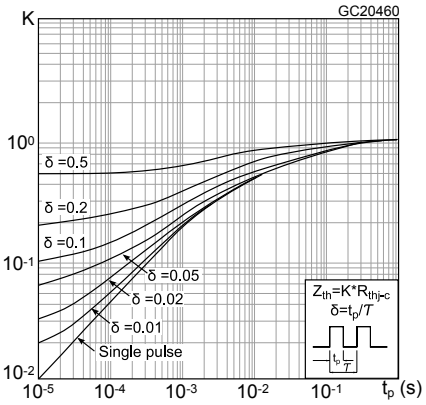


Figure 3. Safe operating area for TO-220FP

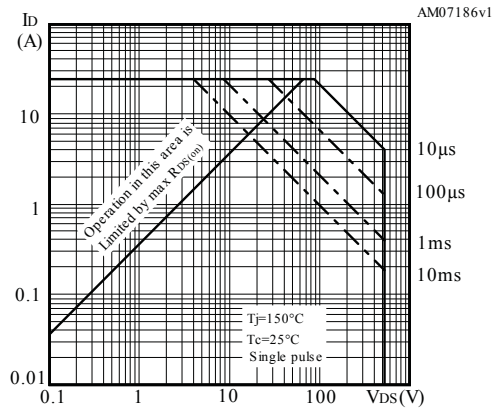


Figure 4. Thermal impedance for TO-220FP

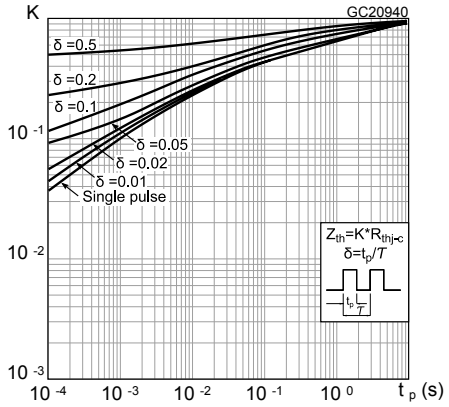


Figure 5. Output characteristics

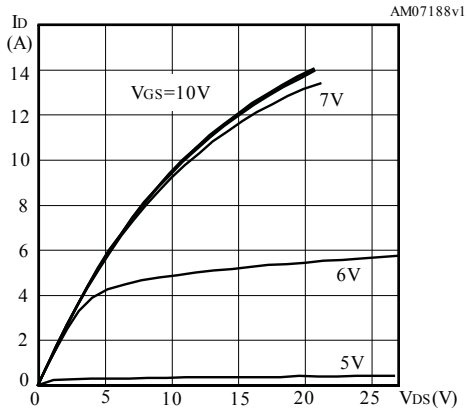


Figure 6. Transfer characteristics

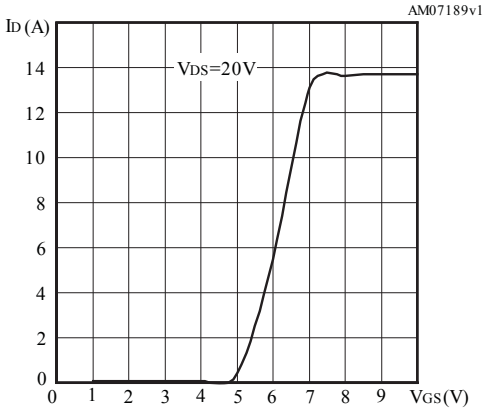


Figure 7. Gate charge vs gate-source voltage

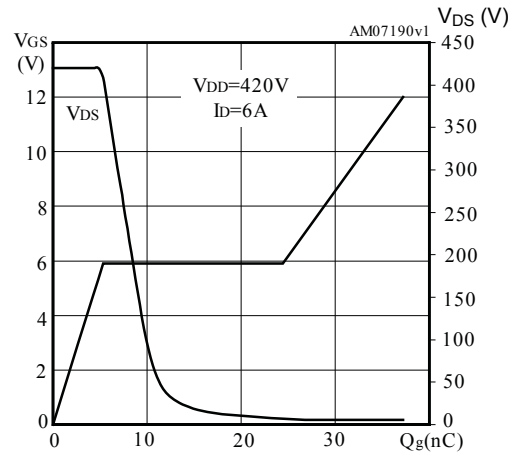


Figure 8. Static drain-source on-resistance

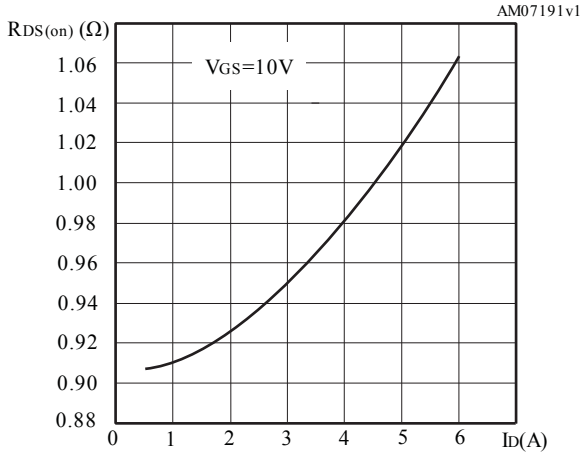


Figure 9. Capacitance variations

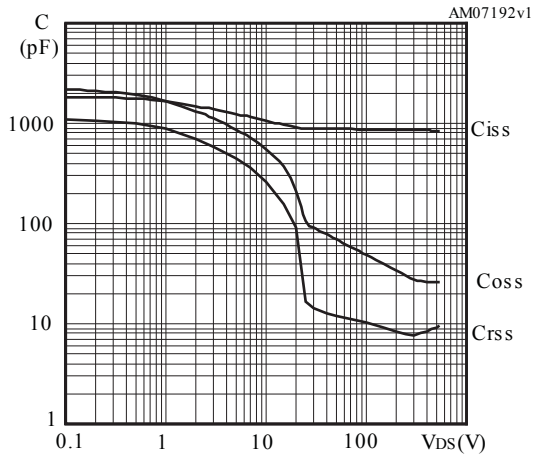


Figure 10. Output capacitance stored energy

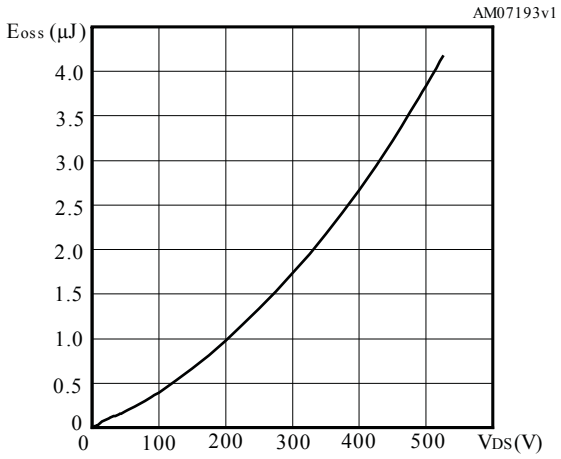


Figure 11. Normalized gate threshold voltage vs temperature

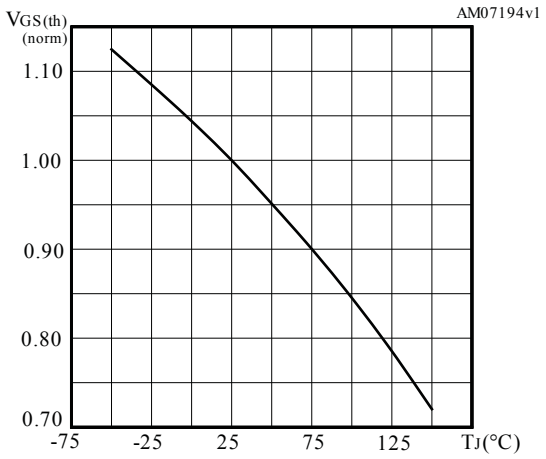


Figure 12. Normalized on-resistance vs temperature

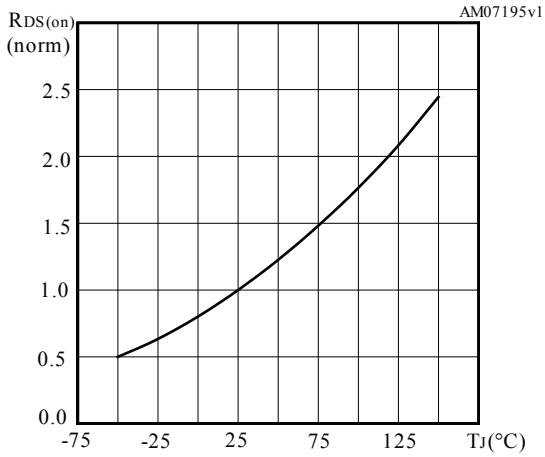


Figure 13. Source-drain diode forward characteristics

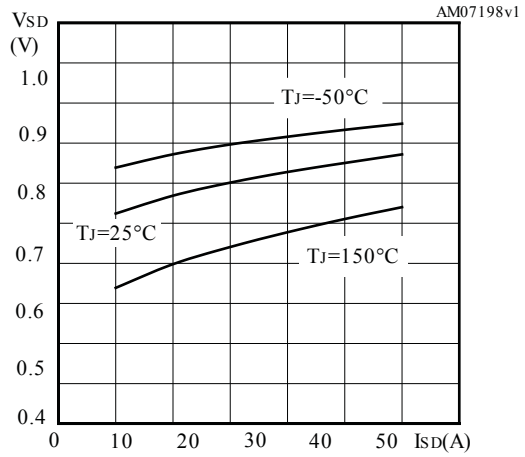


Figure 14. Normalized $V_{(BR)DSS}$ vs temperature

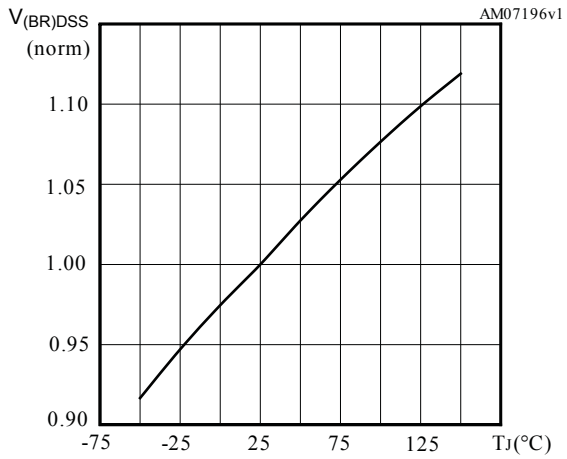
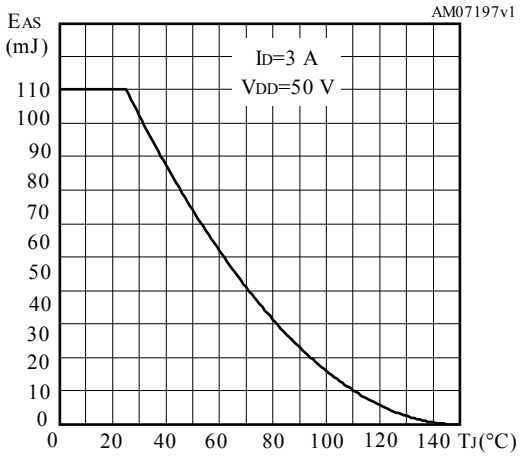


Figure 15. Maximum avalanche energy vs starting T_J



3 Test circuits

Figure 16. Test circuit for resistive load switching times

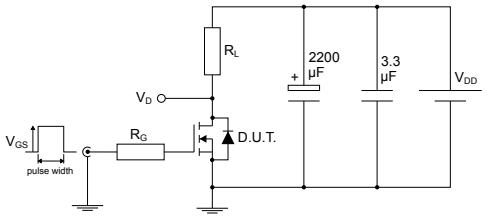


Figure 17. Test circuit for gate charge behavior

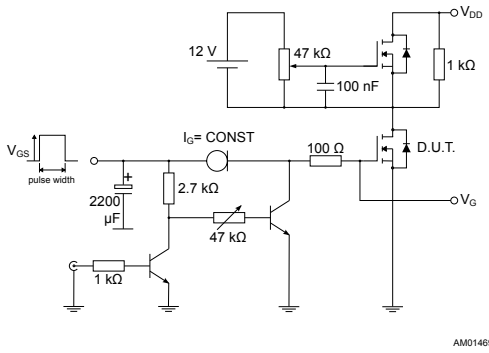


Figure 18. Test circuit for inductive load switching and diode recovery times

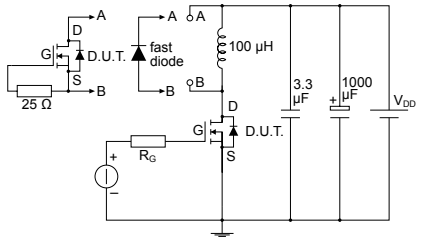


Figure 19. Unclamped inductive load test circuit

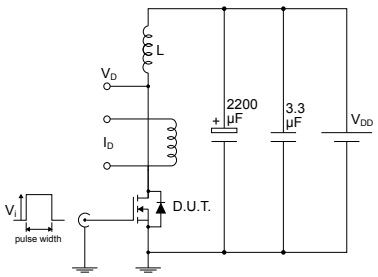


Figure 20. Unclamped inductive waveform

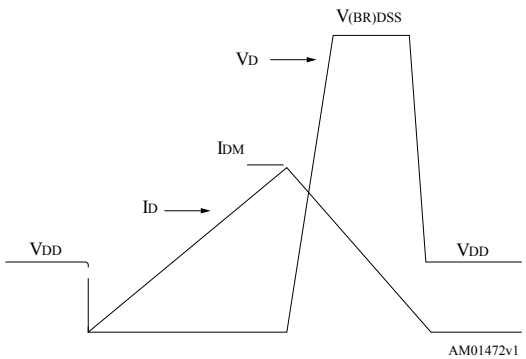
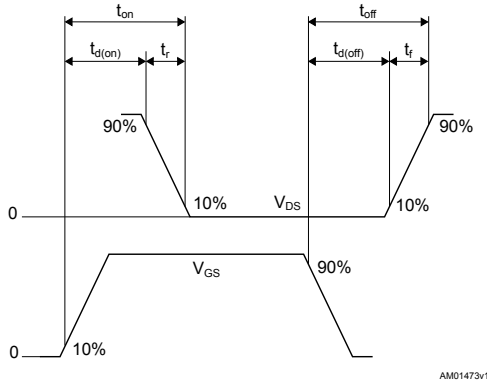


Figure 21. Switching time waveform



4 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

4.1 DPAK (TO-252) type A2 package information

Figure 22. **DPAK (TO-252) type A2 package outline**

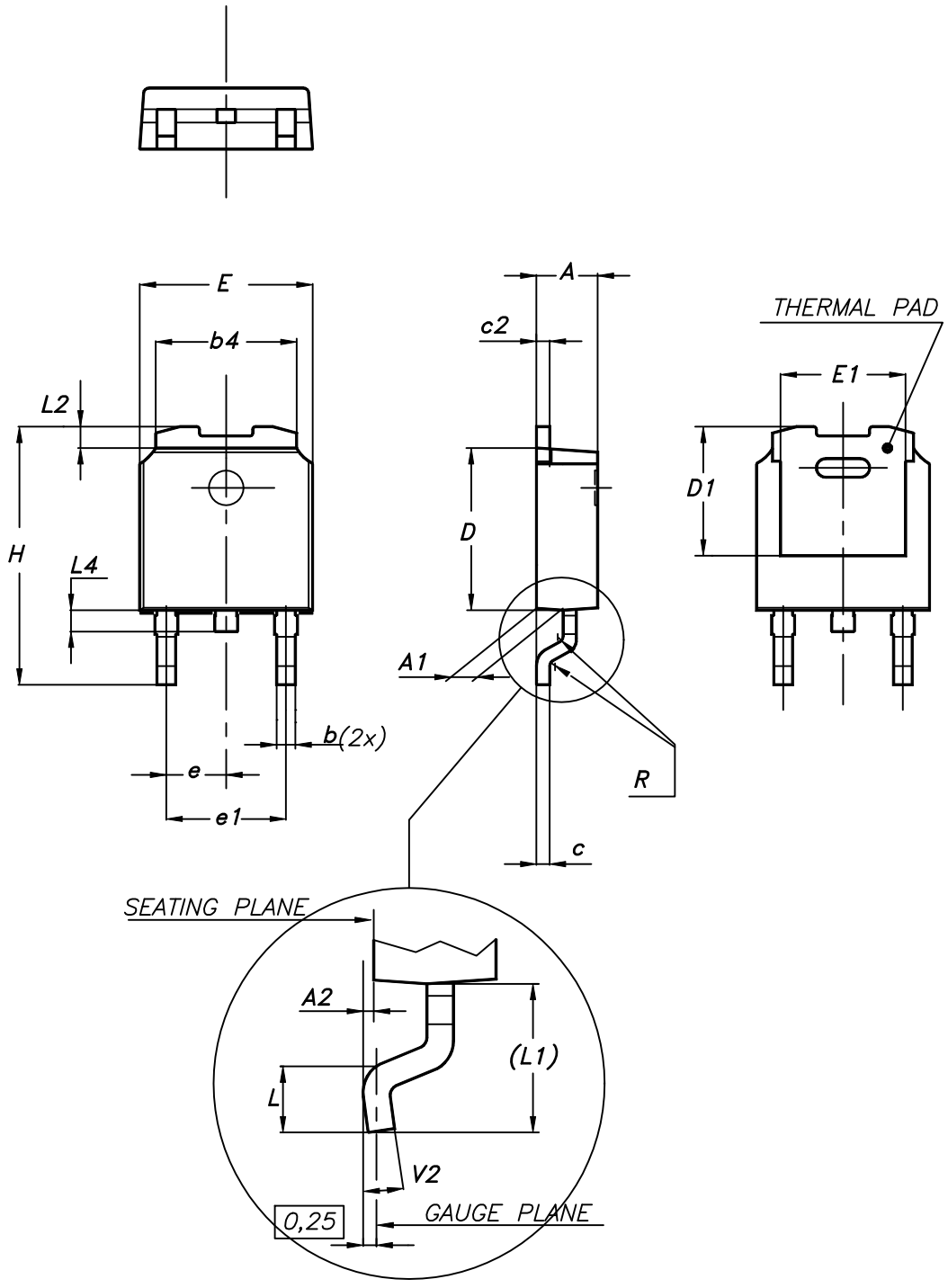
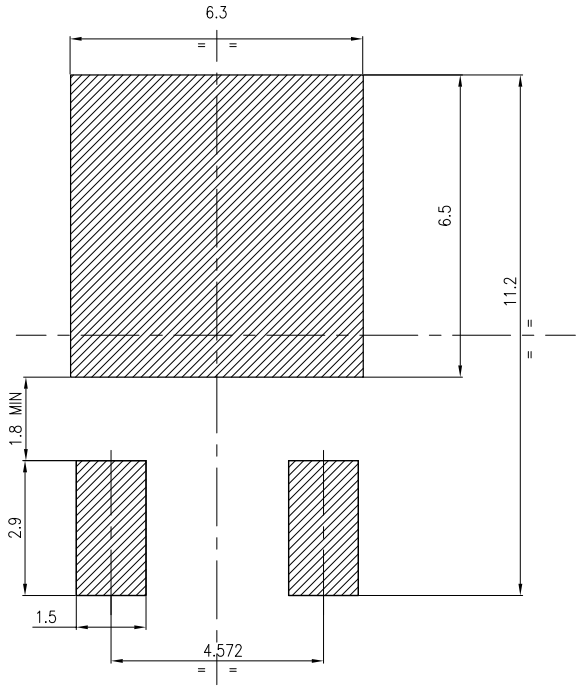


Table 8. **DPAK (TO-252) type A2 mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	2.20		2.40
A1	0.90		1.10
A2	0.03		0.23
b	0.64		0.90
b4	5.20		5.40
c	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
D1	4.95	5.10	5.25
E	6.40		6.60
E1	5.10	5.20	5.30
e	2.159	2.286	2.413
e1	4.445	4.572	4.699
H	9.35		10.10
L	1.00		1.50
L1	2.60	2.80	3.00
L2	0.65	0.80	0.95
L4	0.60		1.00
R		0.20	
V2	0°		8°

Figure 23. **DPAK (TO-252) recommended footprint (dimensions are in mm)**



4.2 DPAK (TO-252) packing information

Figure 24. **DPAK (TO-252) tape outline**

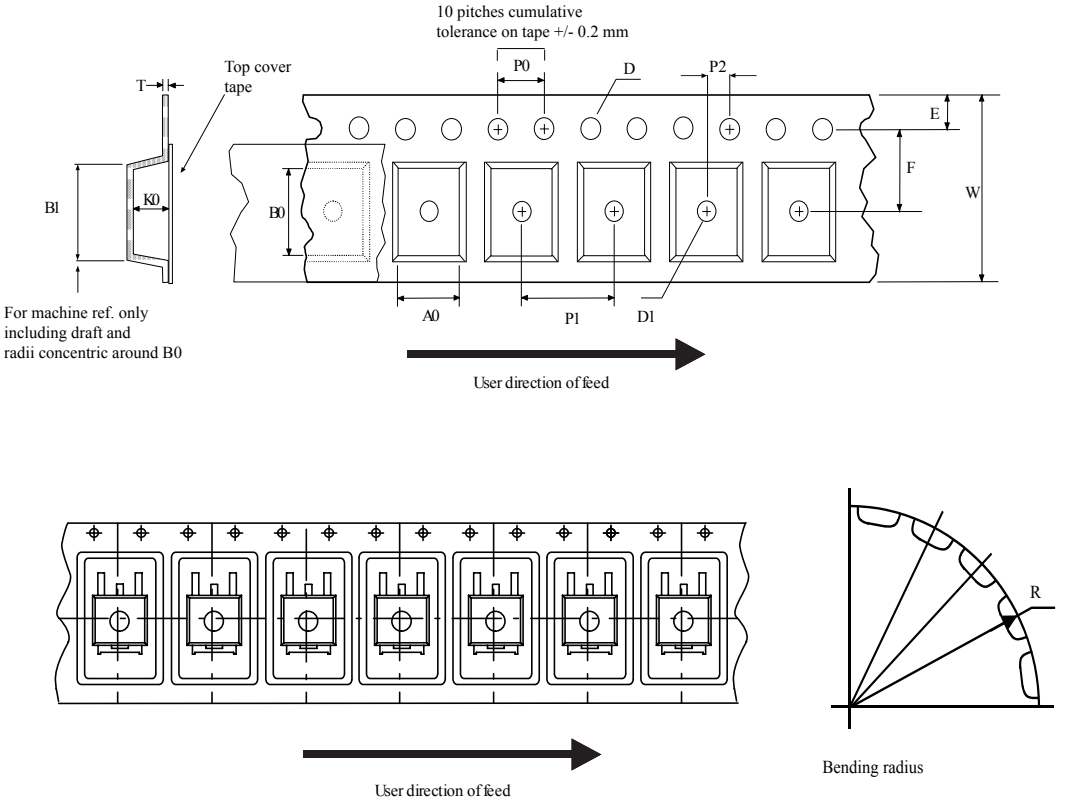


Figure 25. **DPAK (TO-252) reel outline**

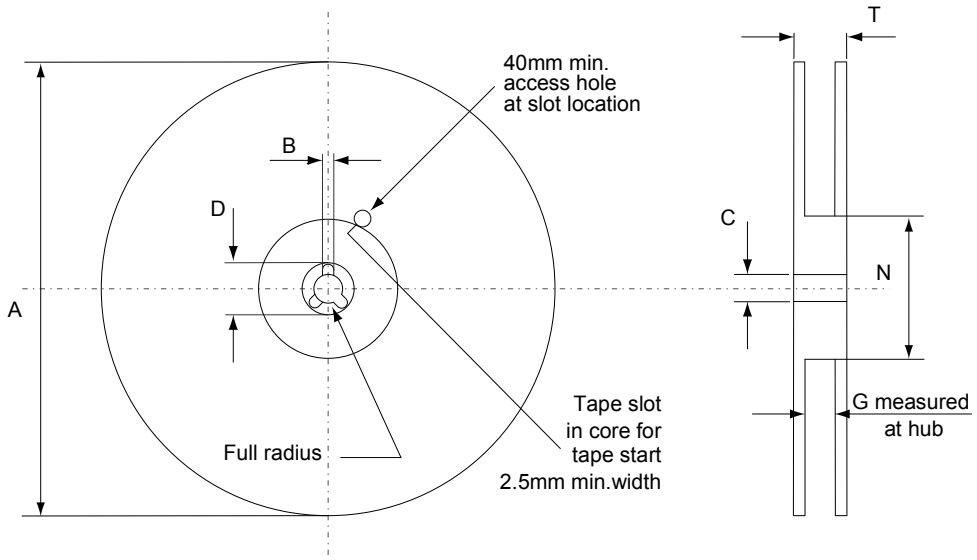


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Table 9. **DPAK (TO-252) tape and reel mechanical data**

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	6.8	7	A		330
B0	10.4	10.6	B	1.5	
B1		12.1	C	12.8	13.2
D	1.5	1.6	D	20.2	
D1	1.5		G	16.4	18.4
E	1.65	1.85	N	50	
F	7.4	7.6	T		22.4
K0	2.55	2.75			
P0	3.9	4.1	Base qty.		2500
P1	7.9	8.1	Bulk qty.		2500
P2	1.9	2.1			
R	40				
T	0.25	0.35			
W	15.7	16.3			

4.3 TO-220FP package information

Figure 26. **TO-220FP package outline**

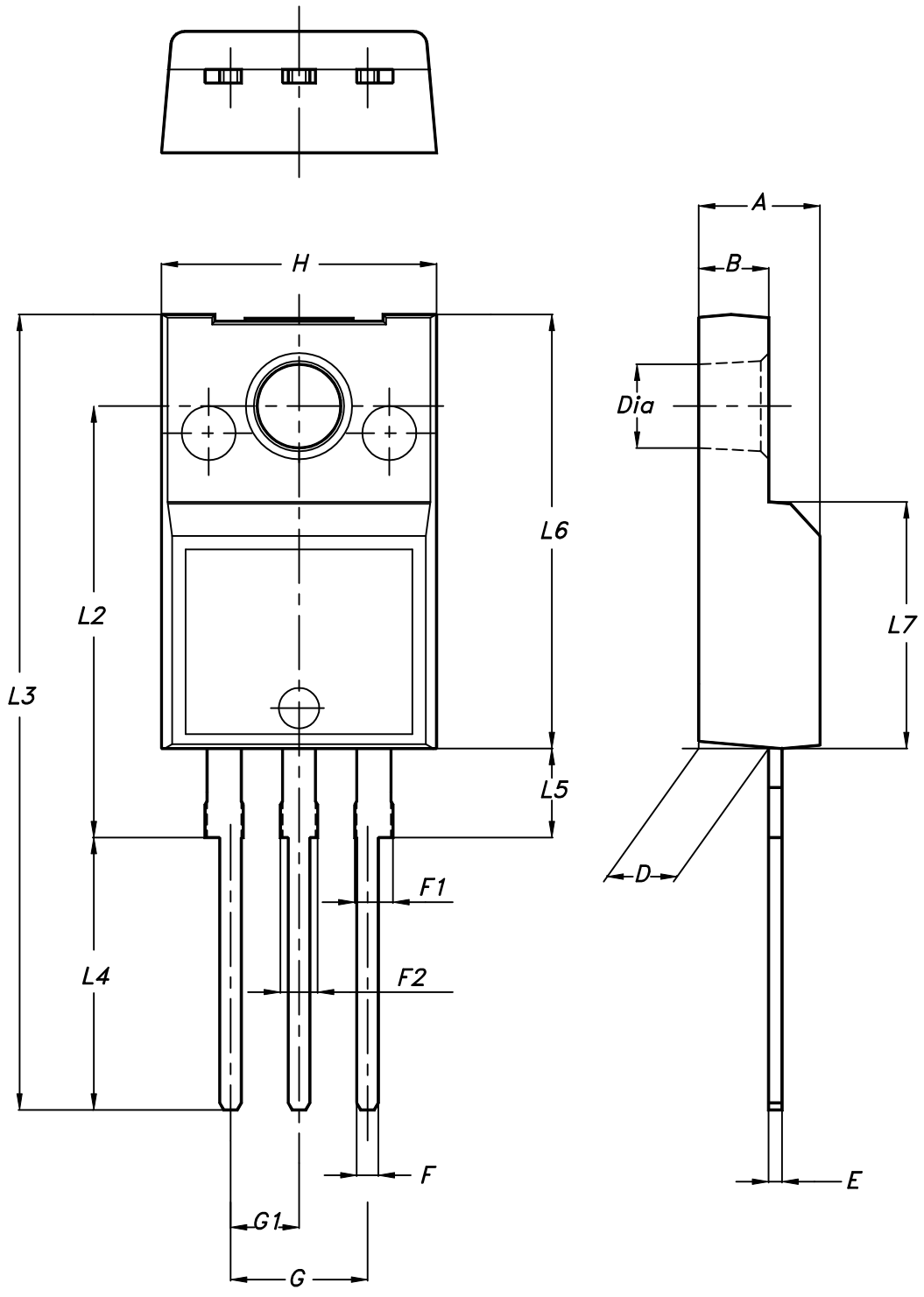

Table 10. **TO-220FP package mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.4		4.6
B	2.5		2.7
D	2.5		2.75
E	0.45		0.7
F	0.75		1
F1	1.15		1.70
F2	1.15		1.70
G	4.95		5.2
G1	2.4		2.7
H	10		10.4
L2		16	
L3	28.6		30.6
L4	9.8		10.6
L5	2.9		3.6
L6	15.9		16.4
L7	9		9.3
Dia	3		3.2

Revision history

Table 11. **Document revision history**

Date	Version	Changes
09-Oct-2009	1	First release
20-Oct-2010	2	Document status promoted from preliminary data to datasheet
01-Oct-2018	3	The part number STP7N52DK3 has been moved to a separate datasheet and the document has been updated accordingly. Updated Section 4 Package information. Minor text changes

Contents

单击下面可查看定价，库存，交付和生命周期等信息

>>STMicro(意法半导体)